

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-6 (canceled)

7. (original) A method for detecting diamonds dislodging from the CMP machine dresser comprising the steps of:
providing a substrate, in which a first conductive layer and a second conductive layer are respectively disposed and isolated, and mounting a plurality of diamonds in the first conductive layer and the second conductive layer, and disposing a bonding layer for attaching the diamonds to the substrate; and
detecting whether or not the short circuit of the first conductive layer to the second conductive layer occurs, so as to determine whether any of the diamonds dislodges;
wherein, the short circuit of the first conductive layer to the second conductive layer occurs when any of the diamonds dislodges and conductive materials penetrate the original position of the diamonds.

8. (original) The method as recited in claim 7, further comprising a step of using a detecting circuit connected to the first conductive layer and the second conductive layer, then feeding back to the chemical mechanical polishing machine when the short circuit

Preliminary Amendment
Divisional of USSN 10/153,348
May 5, 2004
Page 4

of the first conductive layer to the second conductive layer occurs.

9. (original) The dresser as recited in claim 7, wherein the conductive layer comprises metals or alloys.

10. (original) The method as recited in claim 7, wherein the conductive materials comprise a polishing slurry.

11. (original) The method as recited in claim 7, wherein the conductive materials comprise water.

12. (original) The method as recited in claim 7, wherein the detecting circuit comprises a low voltage and current circuit.